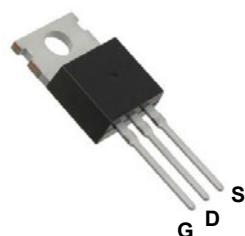
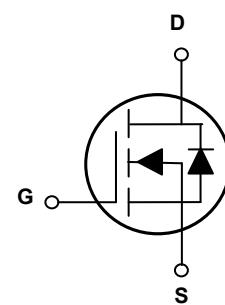


Main Product Characteristics

| | |
|---------------|-------|
| $V_{(BR)DSS}$ | 500V |
| $R_{DS(ON)}$ | 0.19Ω |
| I_D | 20A |



TO-220



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- $\text{Q}_\text{off} < 1 \mu\text{A}$ at $V_\text{GS} = 0$ V
- $\text{Q}_\text{ch} < 1 \mu\text{A}$ at $V_\text{GS} = 0$ V
- Fast switching and reverse body recovery



Description

The GSFH5020 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|-----------------|-------------|---------------------------|
| Drain-Source Voltage | V_{DSS} | 500 | V |
| Gate-Source Voltage | V_{GSS} | ± 30 | V |
| Continuous Drain Current @ Steady-State ¹ , $T_C=25^\circ\text{C}$ | I_D | 20 | A |
| Continuous Drain Current @ Steady-State, $T_C=100^\circ\text{C}$ | | 13 | A |
| Pulsed Drain Current ² | I_{DM} | 80 | A |
| Single Pulsed Avalanche Energy ³ | E_{AS} | 1596 | mJ |
| Power Dissipation, $T_A=25^\circ\text{C}$ | P_D | 252 | W |
| Linear Derating Factor, $T_A=25^\circ\text{C}$ | | 2.02 | W/ $^\circ\text{C}$ |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 0.49 | $^\circ\text{C}/\text{W}$ |
| Junction to Ambient (PCB Mounted, Steady-State) ⁴ | $R_{\theta JA}$ | 50 | $^\circ\text{C}/\text{W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|---|-----------------------------|---|------|------|-----------|---------------|
| On/Off Characteristic | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$ | 500 | - | - | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{\text{DS}}=500\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| | | $T_J=125^\circ\text{C}$ | - | - | 50 | |
| Gate-Source Forward Leakage | I_{GSS} | $V_{\text{GS}}=\pm 30\text{V}$ | - | - | ± 100 | nA |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$ | 2.1 | 3 | 3.9 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}}=10\text{V}, I_D=10\text{A}$ | - | 0.19 | 0.26 | Ω |
| Gate Resistance | R_g | f=1.0MHz | - | 5.6 | - | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$ | - | 2687 | - | pF |
| Output Capacitance | C_{oss} | | - | 355 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 10.5 | - | pF |
| Total Gate Charge | Q_g | $V_{\text{DS}}=400\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$ | - | 49.5 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 14.3 | - | nC |
| Gate-Drain ("Miller") Charge | Q_{gd} | | - | 16.4 | - | nC |
| Switching Characteristics | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DS}}=250\text{V}, I_D=20\text{A}, R_G=10\Omega, V_{\text{GS}}=10\text{V}$ | - | 27.2 | - | nS |
| Turn-On Rise Time | t_r | | - | 47.5 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 78.2 | - | nS |
| Turn-Off Fall Time | t_f | | - | 41.1 | - | nS |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Continuous Source Current (Body Diode) | I_S | MOSFET symbol showing the integral reverse p-n junction diode. | - | - | 20 | A |
| Source Pulse Current (Body Diode) | I_{SM} | | - | - | 80 | A |
| Diode Forward Voltage | V_{SD} | $V_{\text{GS}}=0\text{V}, I_S=20\text{A}$ | - | - | 1.4 | V |
| Reverse Recovery Time | t_{rr} | $T_J=25^\circ\text{C}, I_F=20\text{A}, dI_F/dt= 100\text{A}/\mu\text{s}$ | - | 570 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 5.4 | - | μC |

Notes:

1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
2. Repetitive rating: pulse width limited by max. junction temperature.
3. $L=30\text{mH}, I_{AS}=9.9\text{A}, V_{DD}=50\text{V}, T_J=25^\circ\text{C}$.
4. Device mounted on FR-4PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Electrical and Thermal Characteristic Curves

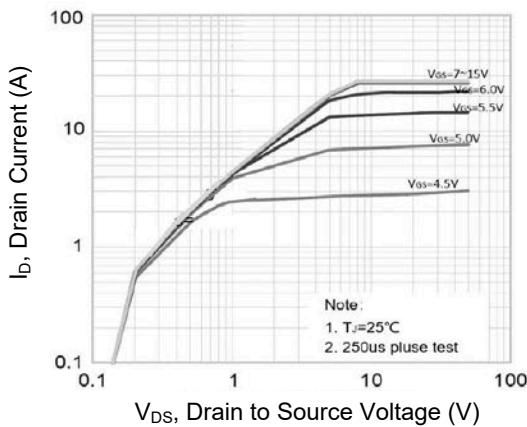


Figure 1. Output Characteristics

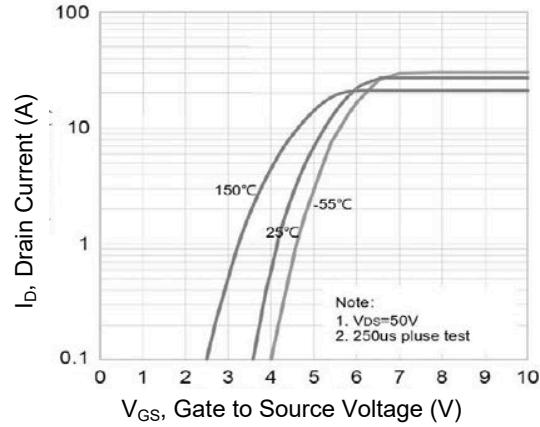


Figure 2. Transfer Characteristics

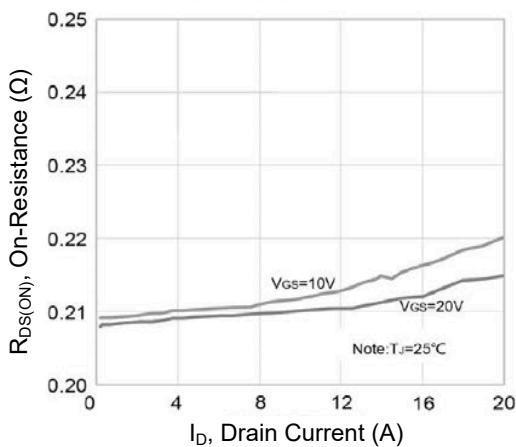


Figure 3. $R_{DS(ON)}$ vs. Drain Current

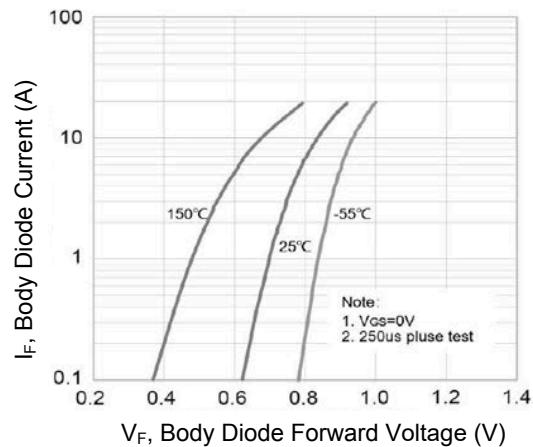


Figure 4. Body Diode Characteristics

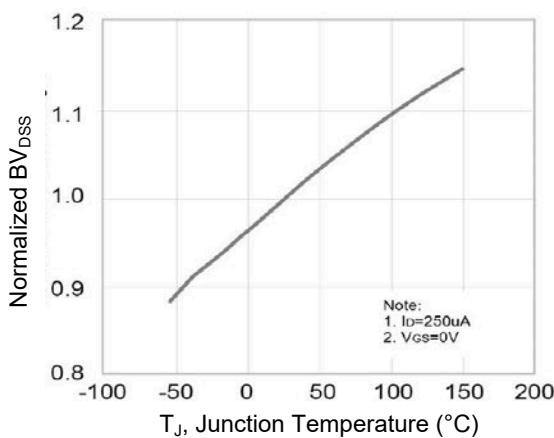


Figure 5. Normalized BV_{DSS} vs. Junction Temperature

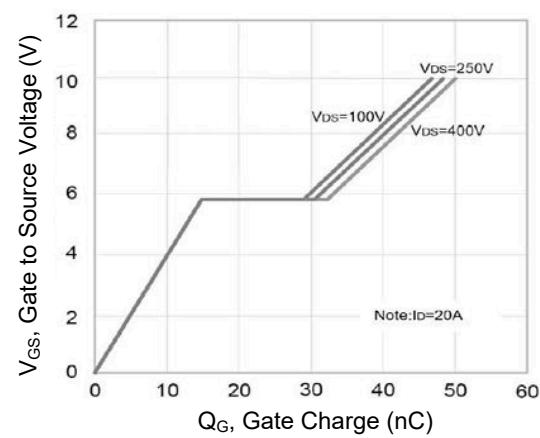


Figure 6. Gate Charge

Typical Electrical and Thermal Characteristic Curves

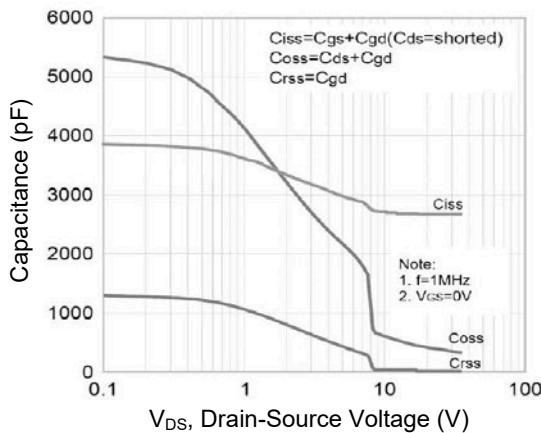


Figure 7. Capacitance Characteristics

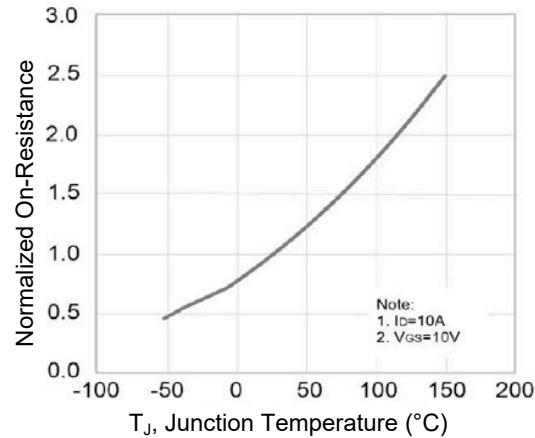


Figure 8. Normalized R_{DS(ON)} vs. T_J

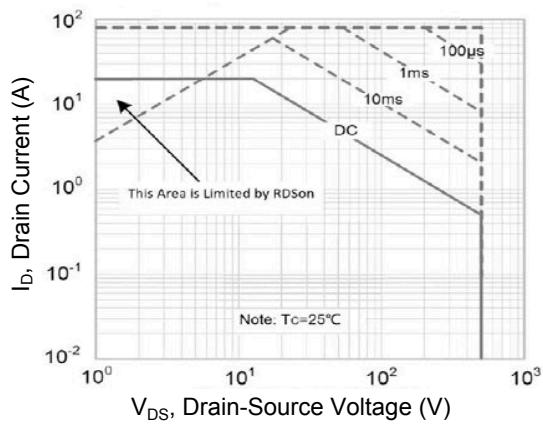
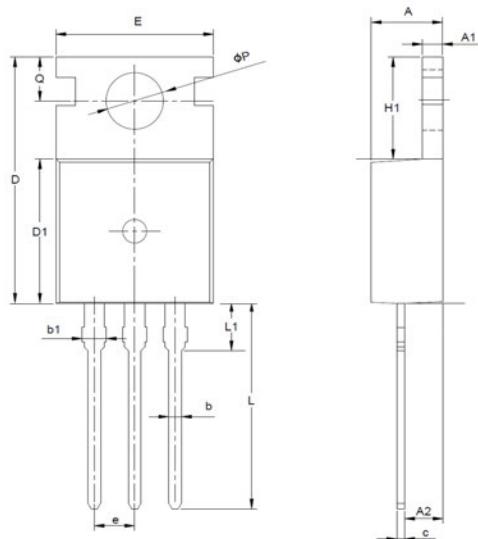


Figure 9. Safe Operation Area

Package Outline Dimensions (TO-220)



| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 4.300 | 4.700 | 0.169 | 0.186 |
| A1 | 1.000 | 1.500 | 0.039 | 0.059 |
| A2 | 1.800 | 2.800 | 0.071 | 0.110 |
| b | 0.600 | 1.000 | 0.024 | 0.039 |
| b1 | 1.000 | 1.600 | 0.039 | 0.063 |
| c | 0.300 | 0.700 | 0.012 | 0.028 |
| D | 15.100 | 16.100 | 0.594 | 0.634 |
| D1 | 8.100 | 10.000 | 0.319 | 0.394 |
| E | 9.600 | 10.400 | 0.378 | 0.410 |
| e | 2.540 BSC | | 0.100 BSC | |
| H1 | 6.100 | 7.000 | 0.240 | 0.276 |
| L | 12.600 | 13.600 | 0.496 | 0.535 |
| L1 | - | 3.950 | - | 0.156 |
| ΦP | 3.400 | 3.900 | 0.134 | 0.154 |
| Q | 2.600 | 3.200 | 0.102 | 0.126 |